Assessment and subject description

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| Óbuda UniversityKandó Kálmán Faculty of Electrical Engineering | | | | | | | Institute of Microelectronics and Technology | | | |
| **Subject name and code:** **Electronic Technology KMEET11AND** **Credits: 2****Full-time, Spring Semester** | | | | | | | | | | |
| Course: Electrical Engineering | | | | | | | | | | |
| Responsible: | Csikósné Dr. Pap Andrea | | | | Teaching staff: | | Gröller György | | | |
| Prerequisites: | | | KMEVR11AND | | | | | | | |
| Contact hours per week: | | Lecture: 2 | | Class discussion: 0 | | Lab hours: 0 | | | Tutorial: 0 | |
| Assessment and evaluation: | | exam | | | | | | | | |
| **Subject description** | | | | | | | | | | |
| *Aims*: Review materials and processes used in electronic industry. Constructions of microelectronic parts and devices and their manufacturing methods. Basic technologies of electronic interconnections. Microelectronics is one of the main field of hitech. To understand the advanced products is necessary to know their technological background. | | | | | | | | | | |
| *Topics to be covered:* | | | | | | | | | | |
| **Topics** | | | | | | | | **Week** | | **Lessons** |
| ***Introduction to the technology and electronic industry***  Discrete parts, substrates, integrated circuits, modules and devices | | | | | | | | 1 | | 2 |
| ***Manufacturing of Printed Wiring Boards***: patterning; steps of lithography, screen printing, etching, electroless and galvanic plating. | | | | | | | | 2 | | 2 |
| Single and double side PCB; main steps of production. Multilayer PCB-s, coo-laminated and sequential methods. | | | | | | | | 3 | | 2 |
| High Density Interconnections (HDI); new requirements, new processes. Control methods.  Design for Manufacturing (DfM). | | | | | | | | 4 | | 2 |
| ***Encapsulation;*** types and footprint of the electronic parts | | | | | | | | 5 | | 2 |
| ***Manufacturing of the electronic modules****;* ***Surface Mounted Technology (SMT)***  Solder paste printing, shooting of devices, reflow soldering. | | | | | | | | 6 | | 2 |
| SMT II: wave soldering, inspection methods, rework. ESD protection. | | | | | | | | 7 | | 2 |
| test | | | | | | | | 8 | | 2 |
| ***Hybrid Integrated Circuits (HIC)***  *Thin Film HIC:* vacuum deposition methods.  *Thick Film HIC:* screen printing methods  Thin and thick passive circuits, trimming methods  *Multichip Modules:* types, manufacturing methods | | | | | | | | 9 | | 2 |
| Holiday | | | | | | | | 10 | |  |
| ***Introduction to the semiconductor technology:***Materials (silicon and compounds semiconductors)  Main processes of IC technology: lithography, doping, oxidizing, etching, epitaxy and vacuum deposition methods | | | | | | | | 11 | | 2 |
| Holiday | | | | | | | | 12 | |  |
| Micro Electro-Mechanical Systems (MEMS) | | | | | | | | 13 | | 2 |
| Printed electronics: materials and technology | | | | | | | | 14 | | 2 |
| **Assessment and evaluation**  *Requirements of the signature:* The test result better than 40%  *Type of exam*: Written exam  *Evaluation of the exam:* 0 – 49 % 1  50 – 59 % 2  60 – 69 % 3  70 – 84 % 4  85 – 100% 5 | | | | | | | | | | |
| Suggested material Gröller György: Electronic technology (presentations and handouts)  <http://www.uni-obuda.hu/users/grollerg/Electronic-technology/>  *Recommended:* Happy Holden: The HDI Handbook <http://www.hdihandbook.com/download.php> | | | | | | | | | | |
| Comment: | | | | | | | | | | |